

L Number	Hits	Search Text	DB	Time stamp
1	1202	(156/308.2).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2004/05/27 12:06
2	883	(156/309.6).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2004/05/27 12:06
3	1984	((156/308.2).CCLS.) ((156/309.6).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2004/05/27 12:06
4	30	((156/308.2).CCLS.) ((156/309.6).CCLS.)) and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2004/05/27 12:06
-	107	((adhesive or glue or resin) near solder) near3 ball	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2004/05/27 12:05
-	2	solder near plated near resin near ball	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT	2004/02/18 14:26
-	8	("4016328" "4716081" "4811081" "5248739" "5443876" "5510174" "5543585" "5550408").PN.	USPAT	2004/02/18 14:44
-	59	5611884.URPN.	USPAT	2004/02/18 14:45
-	82	(metal or solder) near resin near ball	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/18 14:47